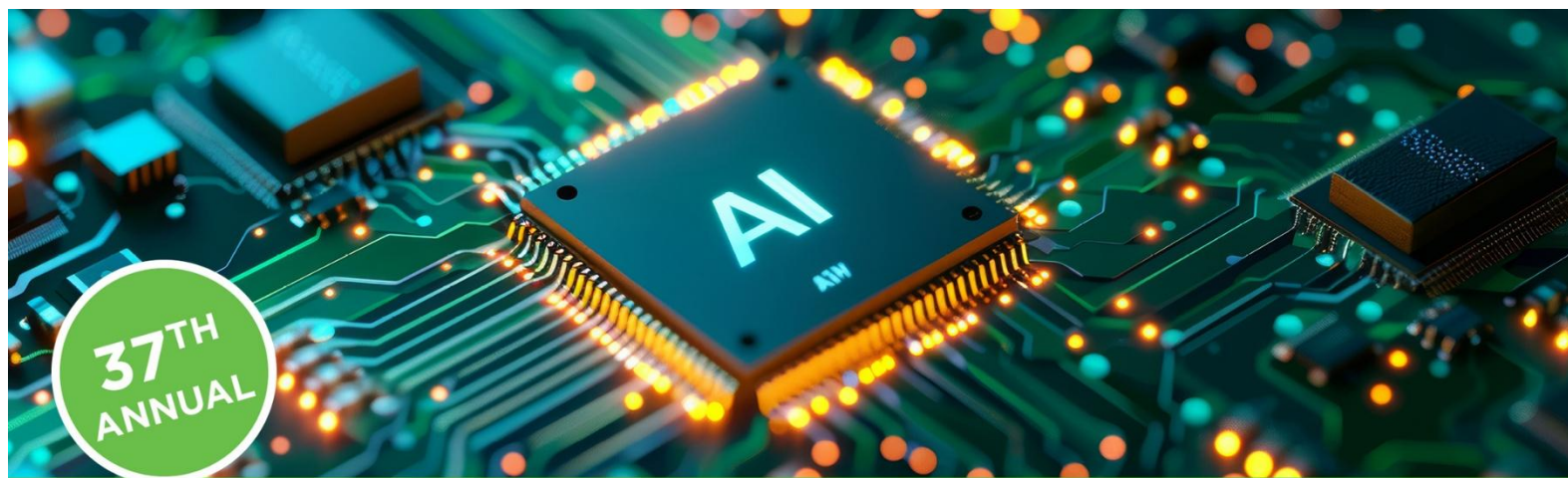




ELECTRONICS PACKAGING SYMPOSIUM

SEPTEMBER 9-10, 2026

Binghamton University • Binghamton, NY

Presented by: IEEC, Binghamton University • CAMM, Binghamton University • GE Aerospace • IBM Research



GE Aerospace



ASE GROUP



Binghamton University, GE Aerospace and IBM Research are proud to host the **37th Annual Electronics Packaging Symposium**. The program will include two days of exciting, invited presentations with a focus on supply chain interconnectivity.

We invite you to join us for this event on Sept. 9-10, 2026, at Binghamton University, N.Y. We look forward to seeing you there.

The symposium brings together leaders in academia, industry and government to network and discuss the latest advances in the field of electronics packaging, and to bring value from the varying viewpoints of each sector.

The program will also include keynote presentations and student poster sessions. The goal of the symposium is to have those who attend walk away with insights, career-building opportunities and the knowledge of having been an integral part of the advancement of the electronics packaging field.

Session topics will include: future of computing for HPC/AI, flexible, additive and wearable electronics, heterogeneous integration, photonics packaging, thermal challenges, advanced substrates and power electronics.

The full agenda is still taking shape.

Visit <https://www.binghamton.edu/ieec/eps> for the most up-to-date details about panel discussions, a special workshop and registration.

Registration page: <http://bit.ly/4446ULa>

TOPICS WILL INCLUDE:

- Future of Computing for HPC/AI
- Flexible, Additive and Wearable Electronics
- Photonics Packaging
- Thermal Challenges
- Advanced Substrates
- Power Electronics
- mmWave / 5G Packaging

For sponsor, exhibit and participant info, contact:

Benson Chan Associate
Director, S3IP
Binghamton University
(607) 777-4349

chanb@binghamton.edu
www.binghamton.edu/ieec